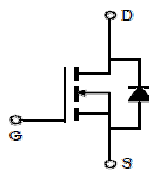




## Features

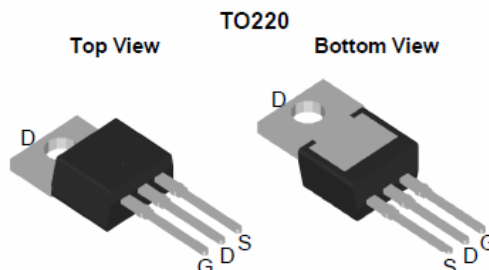
- Lead free and Green Device Available
- Low Rds-on to Minimize Conductive Loss
- High avalanche Current



$V_{DS}$	80V
$R_{DS(on)}$ typ.	3m $\Omega$
max.	4m $\Omega$
$I_D$ (Silicon Limited)	160A
$I_D$ (Package Limited)	120A

## Application

- Power Supply
- DC-DC Converter



## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Param	Maximum	Unit
$V_{DS}$	Drain-to-Source Voltage	80	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 25$	V
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$ (Silicon limited)	A
		$T_C=25^\circ\text{C}$ (Package limited)	
		$T_C=100^\circ\text{C}$	
$I_{DP}$	Pulsed Drain Current	$T_C=25^\circ\text{C}$	-
$I_{AS}$	Avalanche Current ( $L=0.5\text{mH}$ )	43	A
$E_{AS}$	Avalanche Energy ( $L=0.5\text{mH}$ )	462	mJ
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	W
		$T_C=100^\circ\text{C}$	
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55~175	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Max.	Unit
$R_{thJC}$	Thermal resistance, junction to case	0.78	$^\circ\text{C/W}$
$R_{thJA}$	Thermal resistance, junction to ambient	74	$^\circ\text{C/W}$

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu\text{A}$	80	—	—	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=80V, V_{GS}=0V$	—	—	1	$\mu\text{A}$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2	—	4	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$	—	—	$\pm 100$	nA
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=10V, I_D=80A$	—	3	4	m $\Omega$
$G_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=90A$	—	200	—	S



### Diode Characteristics

$V_{SD}$	Diode Forward Voltage	$I_{SD}=40A, V_{GS}=0V$	—	0.9	1.3	V
$I_S$	Diode Continuous Forward Current		—	—	120	A
$t_{rr}$	Reverse Recovery Time	$I_S=90A,$ $di/dt=100A/\mu s$	—	48	—	nS
$Q_{rr}$	Reverse Recovery Charge		—	81	—	nC

### Dynamic Characteristics

$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V,$ Frequency=1MHz	—	1.4	—	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=40V,$ $F=1MHz$	—	8170	—	pF
$C_{oss}$	Output Capacitance		—	925	—	
$C_{rss}$	Reverse Transfer Capacitance		—	712	—	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=40V,$ $I_D=40A,$ $R_g=3\ \Omega,$ $V_{GS}=10V$	—	25	—	nS
$t_r$	Rise Time		—	78	—	
$t_{d(off)}$	Turn-Off Delay Time		—	130	—	
$t_f$	Fall Time		—	76	—	

### Gate Charge Characteristics

$Q_g$	Total Gate Charge	$V_{DS}=64V,$ $V_{GS}=10V,$ $I_D=50A$	—	177	—	nC
$Q_{gs}$	Gate-to-Source Charge		—	22	—	
$Q_{gd}$	Gate-to-Drain Charge		—	83	—	

## Typical Operating Characteristics

Figure 1. Typ. Output Characteristics

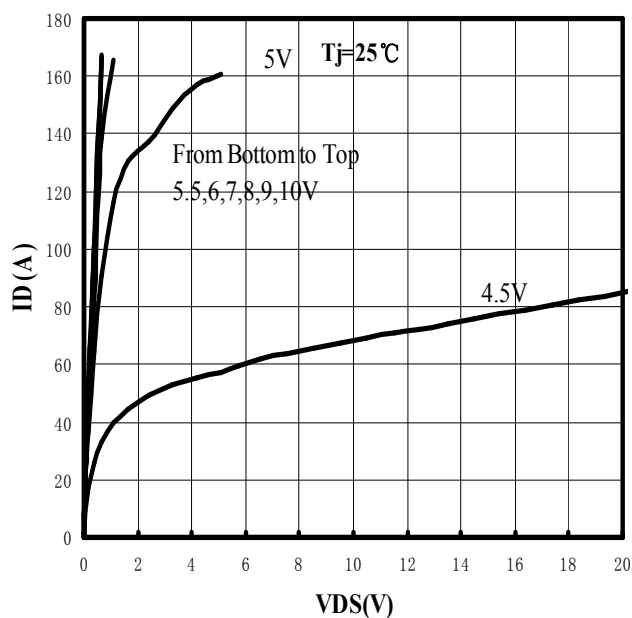


Figure 2. Typ. Output Characteristics

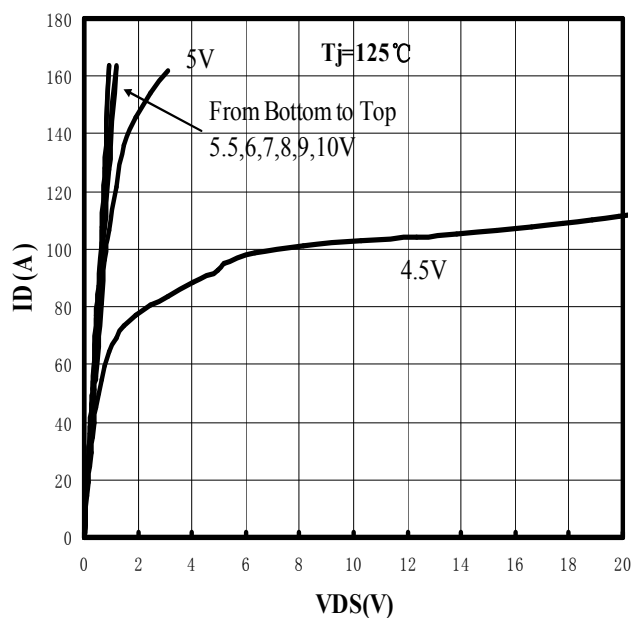


Figure 3. Transfer Characteristics

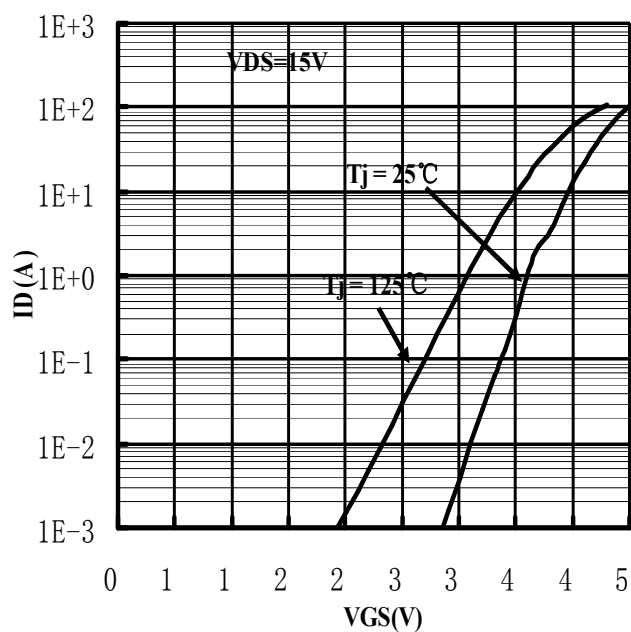
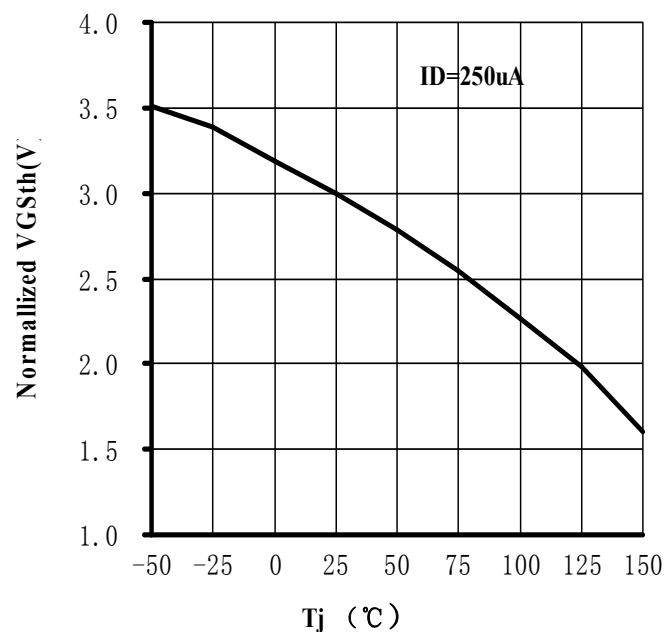


Figure 4. Gate Threshold Voltage Characteristics



## Typical Operating Characteristics

Figure 5. Rdson vs. Drain Current Characteristics

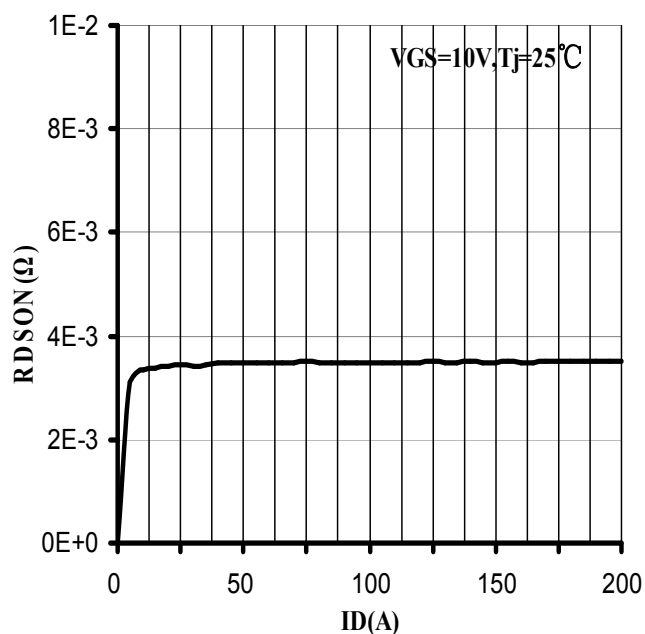


Figure 6. Rdson vs. Junction Tem Characteristics

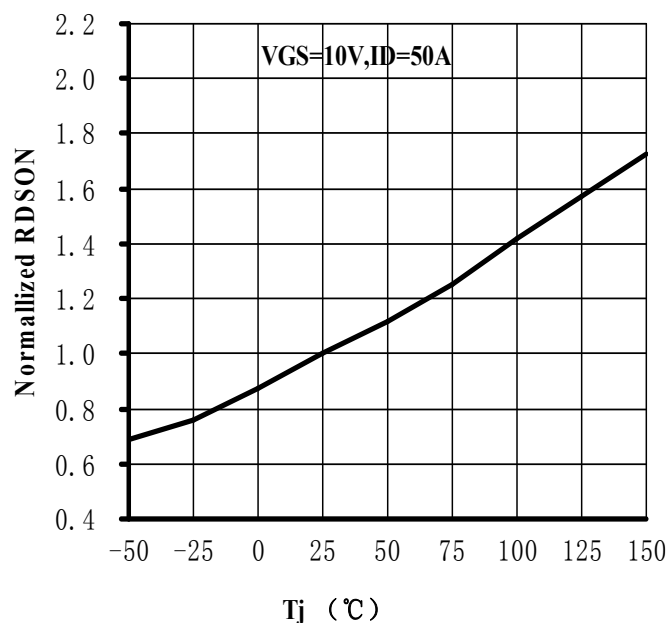


Figure 7. Rdson vs. VGS Characteristics

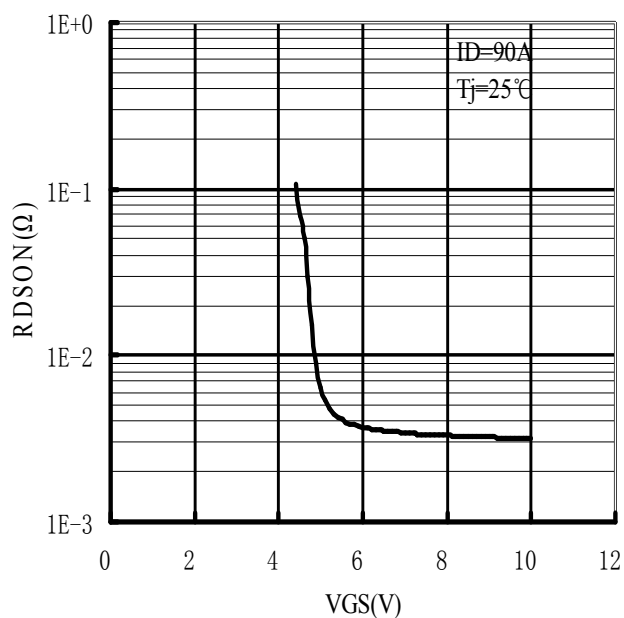
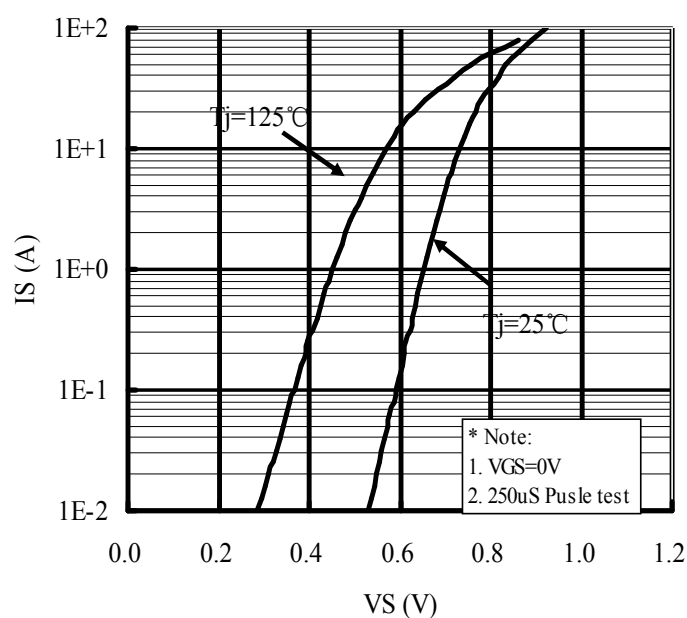


Figure 8. IS vs. VSD Characteristics



## Typical Operating Characteristics

Figure 9. Gate Charge Characteristics

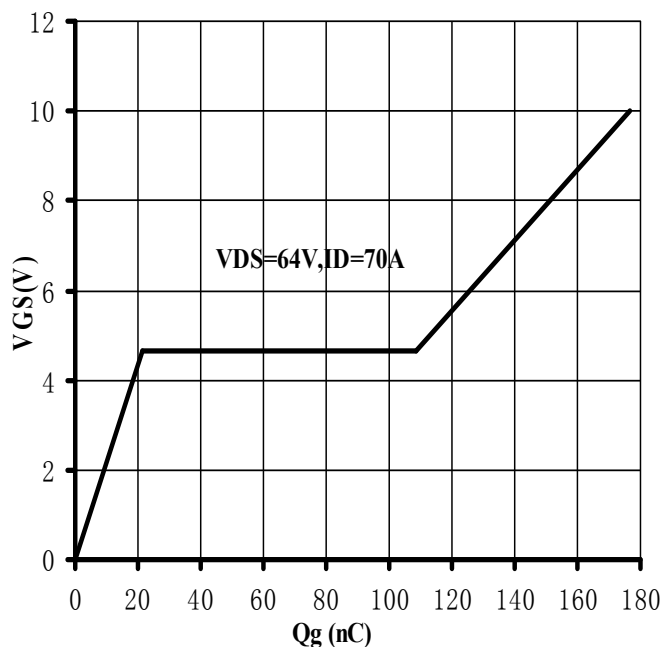


Figure 10. Capacitance Characteristics

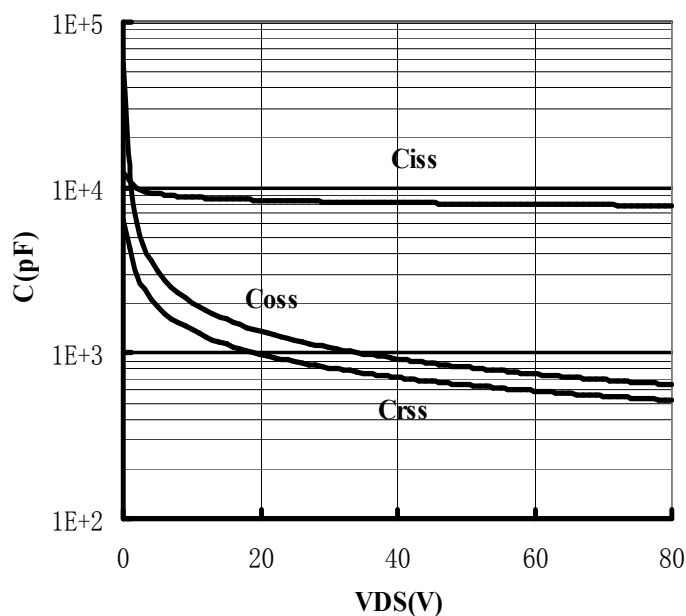
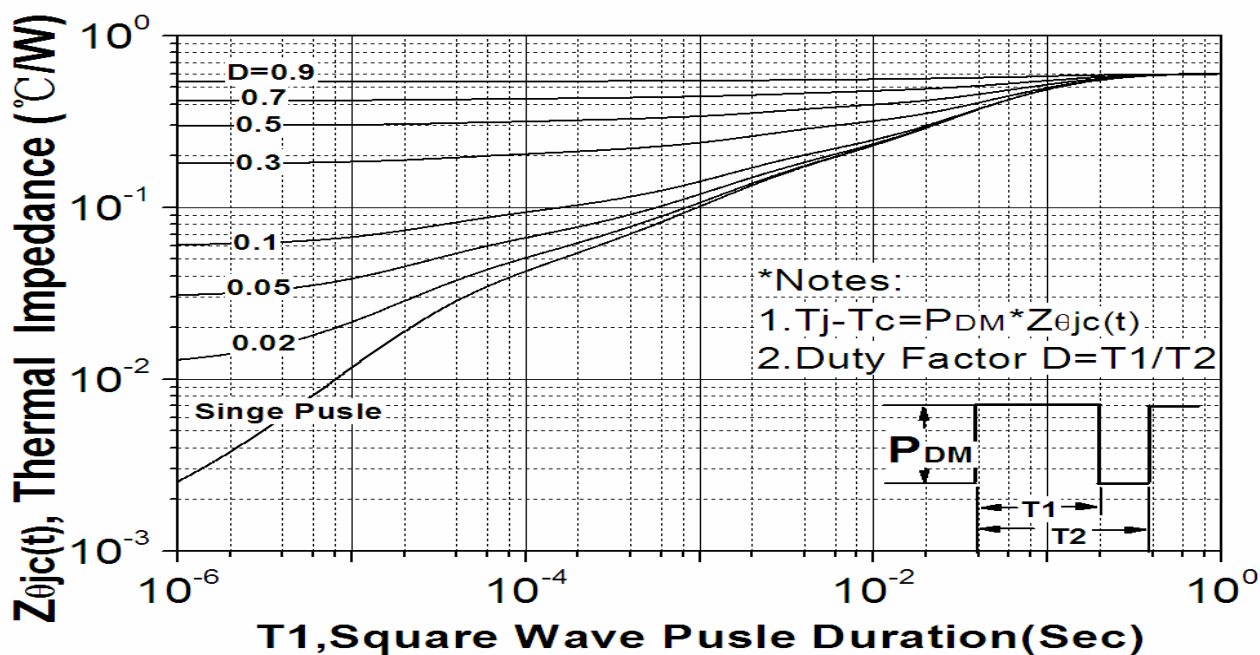
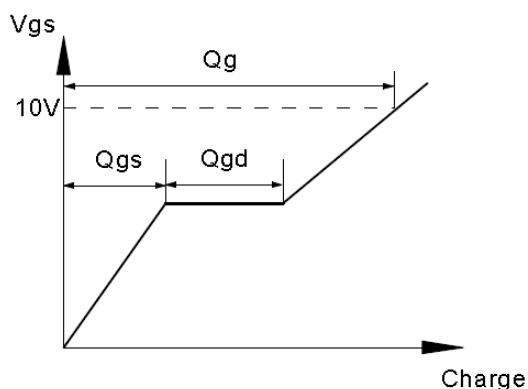
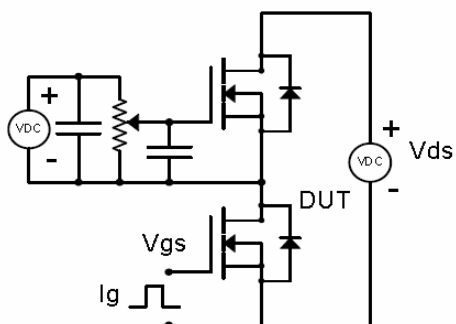


Figure 11. Thermal Resistance Characteristics

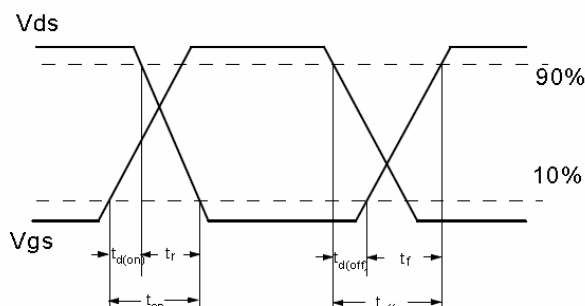
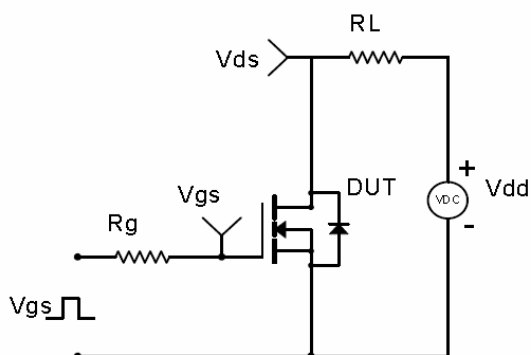


## Test Circuit & Waveform

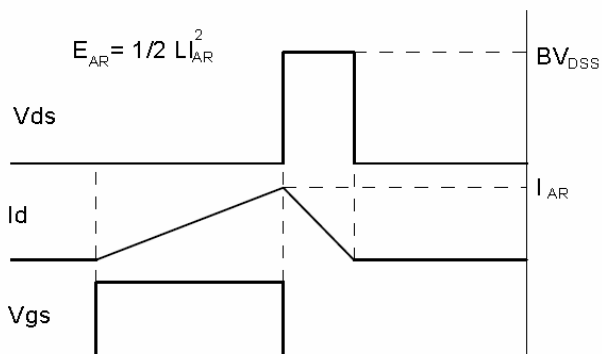
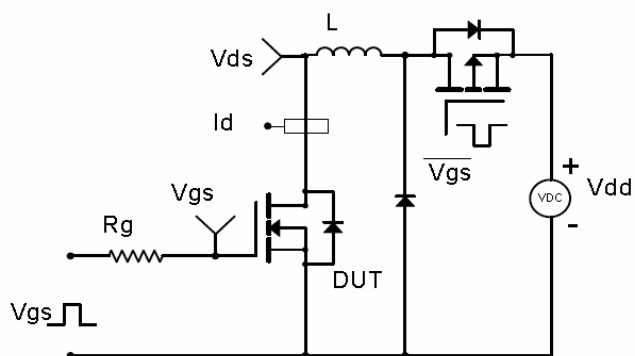
Gate Charge Test Circuit & Waveform



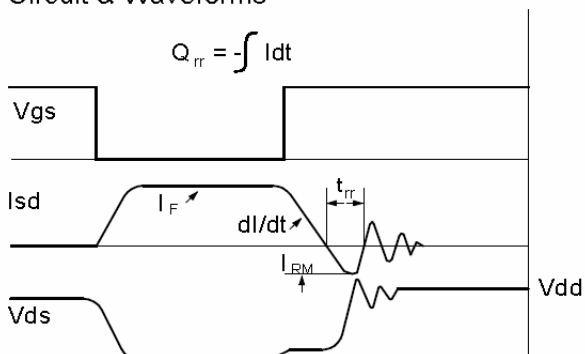
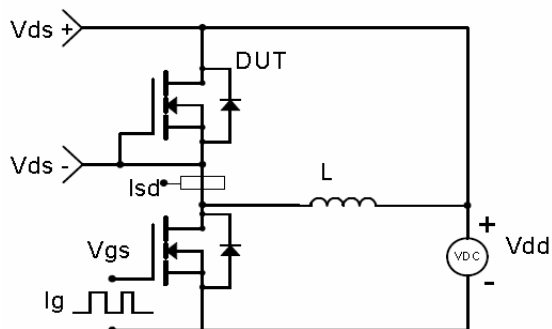
Resistive Switching Test Circuit & Waveforms



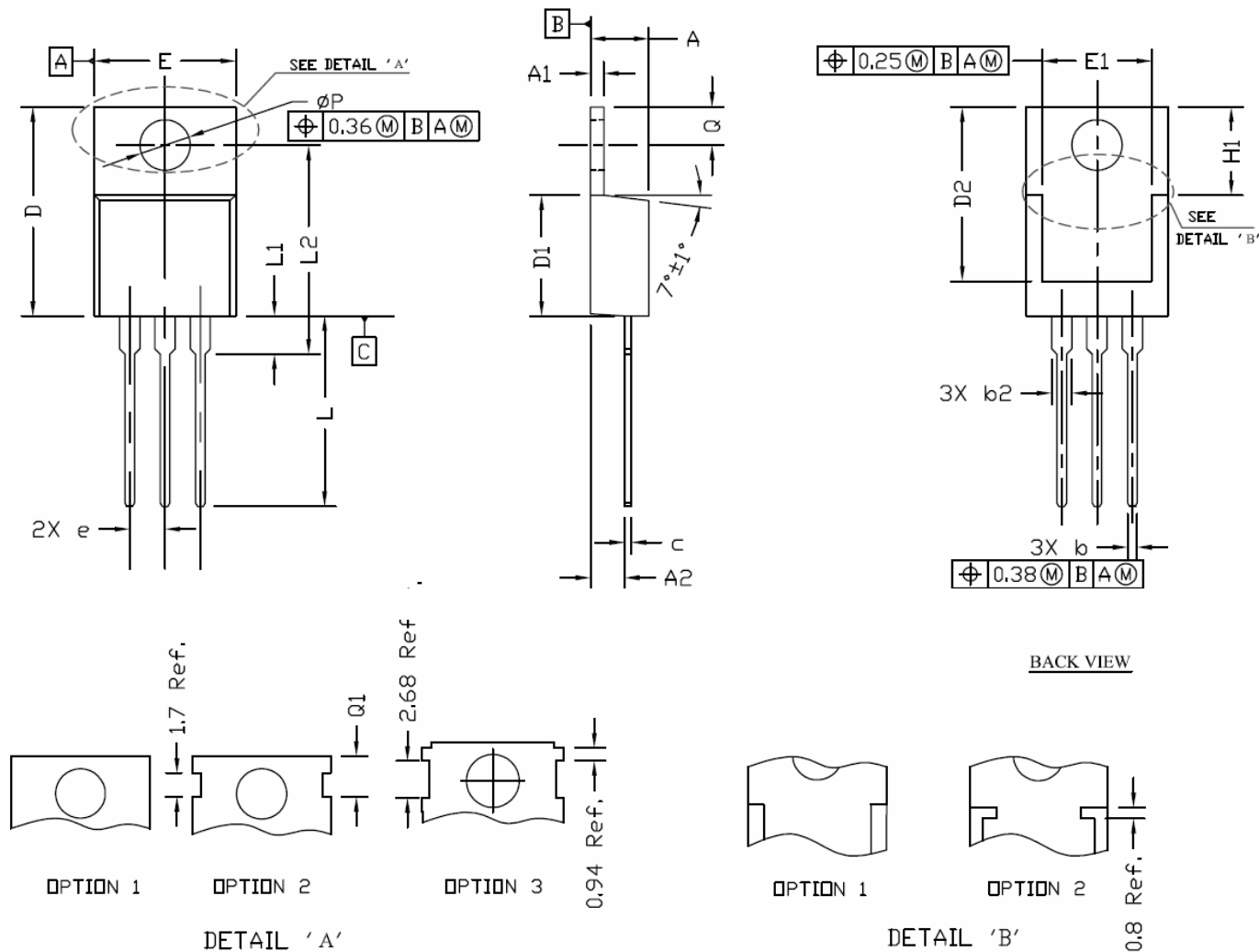
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



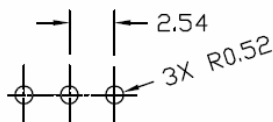
Diode Recovery Test Circuit & Waveforms



## Package Information



### RECOMMENDATION OF HOLE PATTERN



UNIT: mm

#### NOTE

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH SHOULD BE LESS THAN 6 MIL.
2. TOLERANCE 0.100 MILLIMETERS UNLESS OTHERWISE SPECIFIED.
3. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.30	4.45	4.72	0.169	0.175	0.186
A1	1.15	1.27	1.40	0.045	0.050	0.055
A2	2.20	2.67	2.90	0.087	0.105	0.114
b	0.69	0.81	0.95	0.027	0.032	0.037
b2	1.17	1.37	1.45	0.046	0.050	0.068
c	0.36	0.38	0.60	0.014	0.015	0.024
D	14.50	15.44	15.80	0.571	0.608	0.622
D1	8.59	9.14	9.65	0.338	0.360	0.380
D2	11.43	11.73	12.48	0.450	0.462	0.491
e	2.54 BSC			0.100 BSC		
E	9.66	10.03	10.54	0.380	0.395	0.415
E1	6.22	---	---	0.245	---	---
H1	6.10	6.30	6.50	0.240	0.248	0.256
L	12.27	12.82	14.27	0.483	0.505	0.562
L1	2.47	---	3.90	0.097	---	0.154
L2	---	---	16.70	---	---	0.657
Q	2.59	2.74	2.89	0.102	0.108	0.114
$\phi P$	3.50	3.84	3.89	0.138	0.151	0.153
Q1	2.70	---	2.90	0.106	---	0.114